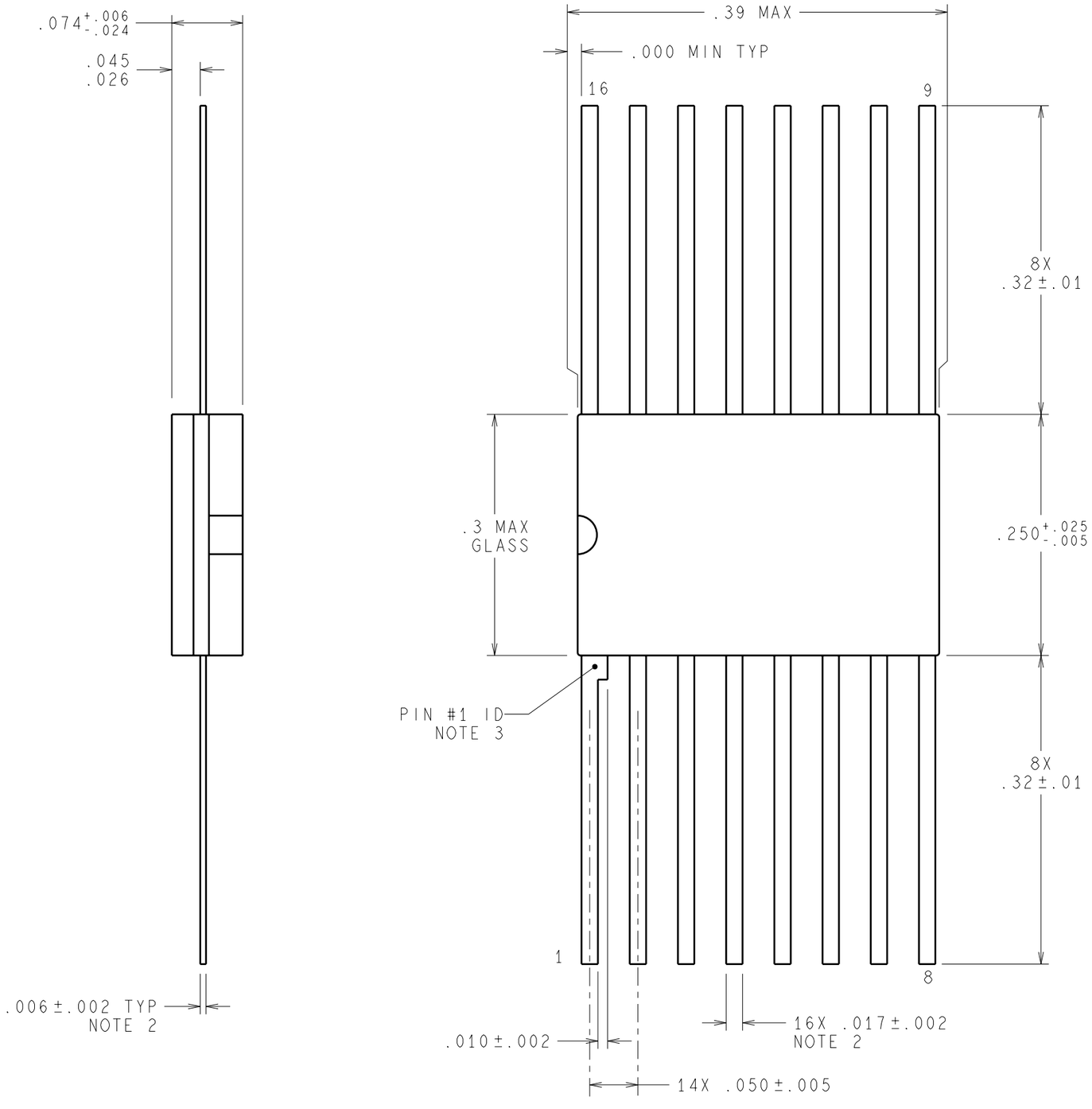
REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
K	REVISE AND REDRAW PER NEW STANDARD	10514	07/28/1994	DEG/AEP
L	.017±.002 WAS .017±.020.	10656	10/21/1994	DEG/CD
M	DIM'S .030+.018/-.004 WAS .030+.010/-.004; .006±.002 WAS .005±.001; REVISE NOTE 4.	199	11/30/2000	MS/CD
N	.005 MIN WAS .000 MIN; CHG DWG FORMAT TO B SIZE	754	08/30/2002	TL/YFT
P	.026+.045 WAS .030 +.018/-.004; UPDATE TITLE & REVISE NOTE 1 PER CURRENT STD	1160	09/10/2003	TL/SWK
R	DIM. .000 MIN WAS .005 MIN	1460	05/04/2004	TL/ACBS
T	REMOVE DIM .013±.005 TYP	1856	07/13/2005	MS/LHC



DIMENSIONS ARE IN INCHES

NOTES: UNLESS OTHERWISE SPECIFIED

1. FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE) (www.national.com).
2. MAXIMUM LIMIT MAY BE INCREASED BY .003 INCHES AFTER LEAD FINISH APPLIED.
3. LEAD 1 IDENTIFICATION SHALL BE:
   a) A NOTCH OR OTHER MARK WITHIN THIS AREA.
   b) A TAB ON LEAD 1, EITHER SIDE.
4. REFERENCE JEDEC REGISTRATION MO-092, VARIATION AC.

MIL-PRF-38535 CONFIGURATION CONTROL

APPROVALS	DATE
DRAWN D.E.Grady	07/28/1994
DFTG. CHK. THANH LEQUANG	07/13/2005
ENGR. CHK. LEE HUA CHONG	07/13/2005

PROJECTION INCH

National Semiconductor
2900 Semiconductor Dr., Santa Clara, CA 95052-8090

CERPACK, .390x.250x.074 BODY, 16 LD, .050 PITCH

SCALE	SIZE	DRAWING NUMBER	REV
NTS	B	(SC)MKT-W16A	T

FORMERLY: N/A

SHEET 1 of 1